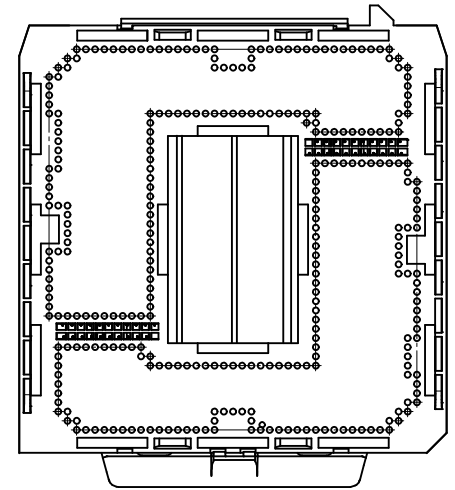


- NOTES:
- MATERIAL:
 - HOUSING AND CAP: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, BLACK COLOR
 - CONTACT: HIGH STRENGTH COPPER ALLOY
 - SOLDER BALL: LEAD FREE SnAg3.0Cu0.5
 - PLATING:
 - 50μ" NICKEL AT PADDLE AND CONTACT AREA.
 - GOLD PLATING THICKNESS AT CONTACT AREA REFER TO TABLE.
 - DATE CODE "YMD**" IS DEFINED AS:
 - "YEAR/MONTH/DAY/MOLEX INTERNAL".
 - PRODUCT SPECIFICATION PS-47596-* APPLIES.
 - PACKAGING SPECIFICATION PK-47596-001 APPLIES.
 - ALL PART NUMBERS COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.
 - "XXX" IS FOR CAVITY # (MOLEX INTERNAL USE)



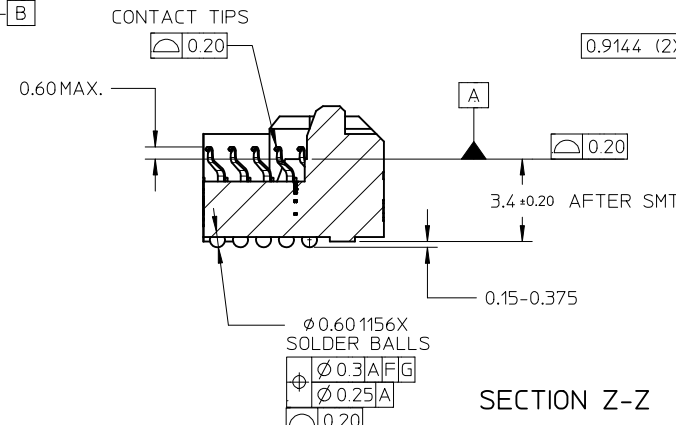
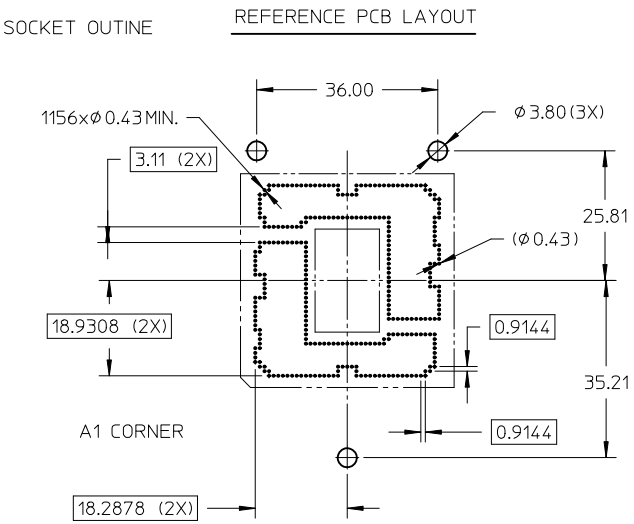
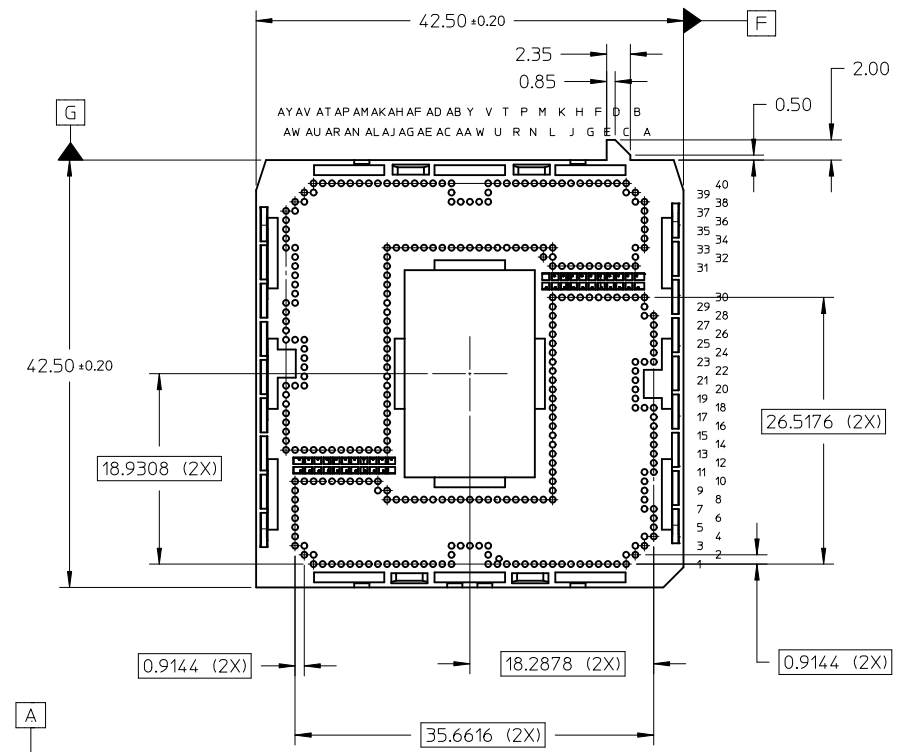
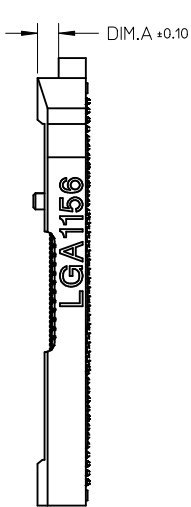
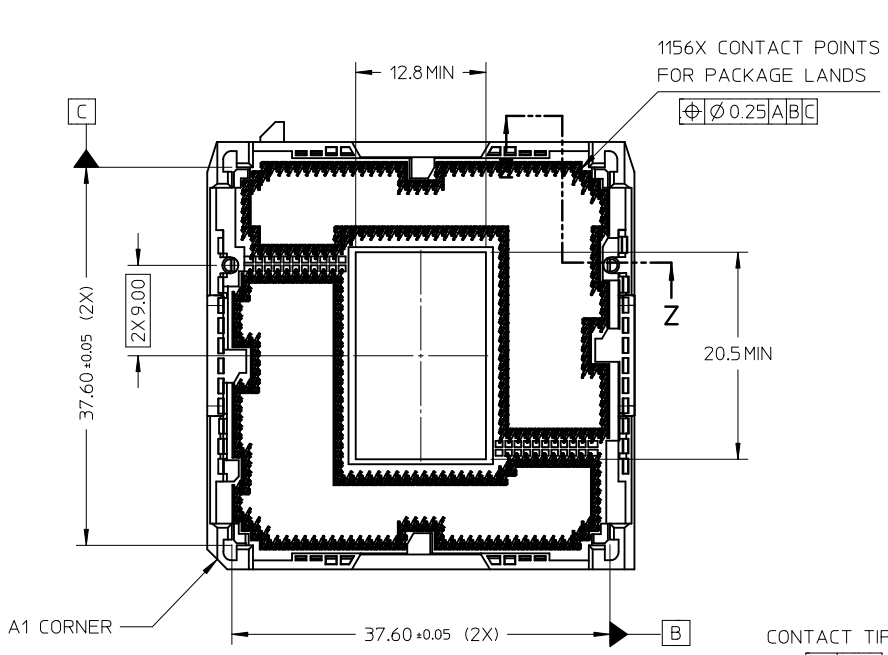
BOTTOM VIEW

ENTER DESCRIPTION EC NO: SH2011-0226 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/01/10 2011/03/03	QUALITY SYMBOLS F=0 E=0 E=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	JL IU	2008/01/01	LGA1156 SOCKET			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED DOCUMENT NO. SD-47596-001 SHEET NO. 1 OF 2			
2 PLACES	± 0.25	± ---	JKACHLIC	2008/02/19						
1 PLACE	± 0.25	± ---	APPROVED BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
ANGULAR ± 1 °			CL IANG	2008/02/19						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE								

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A

F
E
D
C
B
A



PART NO.	FINISHES: CONTACT AREA	DIM.A
475960132	15u" (0.38um) MIN. GOLD	0.75
475960133	30u" (0.76um) MIN. GOLD	0.75
475960532	15u" (0.38um) MIN. GOLD	2.10
475960533	30u" (0.76um) MIN. GOLD	2.10

ENTER DESCRIPTION EC NO: SH2011-0226 DRWN: ZHANG11 2011/01/10 CHKD: APPR: AYIN 2011/03/03	QUALITY SYMBOLS $\nabla F = 0$ $\nabla E = 0$ $\nabla P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION															
		<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table>			mm	INCH		4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± ---	1 PLACE	± 0.25	± ---	DRAWN BY JL IU	DATE 2008/01/01	TITLE LGA1156 SOCKET
			mm	INCH																		
		4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																				
2 PLACES	± 0.25	± ---																				
1 PLACE	± 0.25	± ---																				
ANGULAR ± 1 °		CHECKED BY JKACHLIC	DATE 2008/02/19	MOLEX INCORPORATED																		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY CL IANG	DATE 2008/02/19	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47596-001	SHEET NO. 2 OF 2																

9 8 7 6 5 4 3 2 1